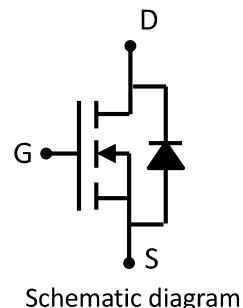


## Feature

- 500V,3A
- $R_{DS\ (ON)} < 3.0 \Omega @ V_{GS}=10V$  TYP:2.6  $\Omega$
- Fast Switching
- Lead free product is acquired
- Excellent  $R_{DS\ (ON)}$  and Low Gate Charge



## Application

- PWM applications
- Load Switch
- Power management



TO-220F

## Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
3N50F	AP3N50F	TO-220F	-	-	1000

## ABSOLUTE MAXIMUM RATINGS ( $T_a=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	500	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Continuous Drain Current ( $T_a = 25^\circ C$ )	$I_D$	3	A
Continuous Drain Current ( $T_a = 100^\circ C$ )	$I_D$	1.8	A
Pulsed Drain Current <sup>(1)</sup>	$I_{DM}$	12	A
Single Pulsed Avalanche Energy <sup>(2)</sup>	$E_{AS}$	45	mJ
Power Dissipation	$P_D$	25	W
Thermal Resistance from Junction to Case	$R_{eJC}$	4.9	$^\circ C/W$
Junction Temperature	$T_J$	150	$^\circ C$
Storage Temperature	$T_{STG}$	-55~+150	$^\circ C$

**MOSFET ELECTRICAL CHARACTERISTICS( $T_a=25^\circ C$  unless otherwise noted)**

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	500	-	-	V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 500V, V_{GS} = 0V$	-	-	1	$\mu A$
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	$\pm 100$	nA
Gate threshold voltage <sup>(3)</sup>	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	3.1	4	V
Drain-source on-resistance <sup>(3)</sup>	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 1.5A$	-	2.6	3.0	$\Omega$
Forward transconductance <sup>(3)</sup>	$g_{FS}$	$V_{DS} = 10V, I_D = 1.5A$	0.5	-	-	S
<b>Dynamic characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 25V, V_{GS} = 0V, f = 1MHz$	-	278	-	pF
Output Capacitance	$C_{oss}$		-	20	-	
Reverse Transfer Capacitance	$C_{rss}$		-	5	-	
<b>Switching characteristics</b>						
Turn-off delay time	$t_{d(off)}$	$V_{DD}=300V, I_D=3A, V_{GS}=10V, R_G=25\Omega$	-	13	-	ns
Total Gate Charge	$Q_g$	$V_{DS}=480V, ID=1A, VGS=10V$	-	4.8	-	nC
Gate-Source Charge	$Q_{gs}$		-	0.7	-	
Gate-Drain Charge	$Q_{gd}$		-	2.7	-	
<b>Source-Drain Diode characteristics</b>						
Diode Forward voltage <sup>(3)</sup>	$V_{DS}$	$V_{GS} = 0V, I_S = 3A$	-	-	1.4	V
Diode Forward current <sup>(4)</sup>	$I_S$		-	-	3	A
Body Diode Reverse Recovery Time	$t_{rr}$	$T_J=25^\circ C, IF=3A, di/dt=100A/us$		190		ns
Body Diode Reverse Recovery Charge	$Q_{rr}$	$T_J=25^\circ C, IF=3A, di/dt=100A/us$		0.53		uc

**Notes:**

1. Repetitive Rating: pulse width limited by maximum junction temperature
2. EAS Condition: $T_J=25^\circ C, V_{DD}=50V, R_G=2.0\Omega, L=10mH$
3. Pulse Test: pulse width $\leq 300\mu s$ , duty cycle $\leq 2\%$
4. Surface Mounted on FR4 Board,  $t \leq 10$  sec

### Typical Characteristics

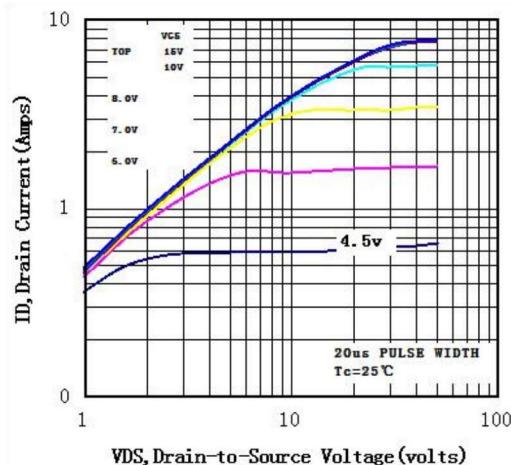


Fig1 Typical Output Characteristics,  $T_c=25^\circ\text{C}$

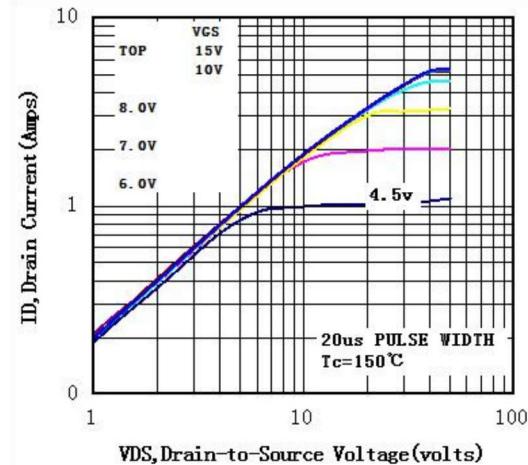


Fig2 Typical Output Characteristics,  $T_c=150^\circ\text{C}$

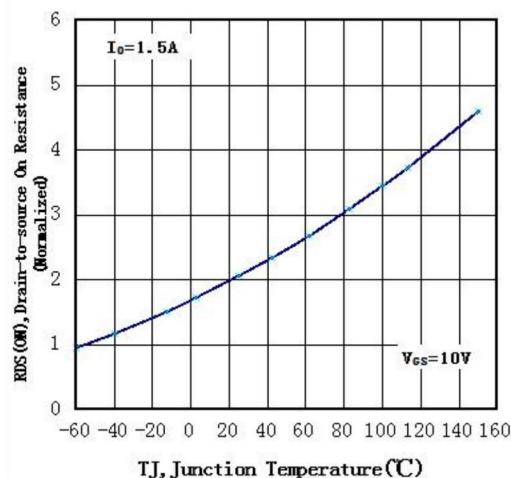


Fig3 Normalized On-Resistance Vs. Temperature

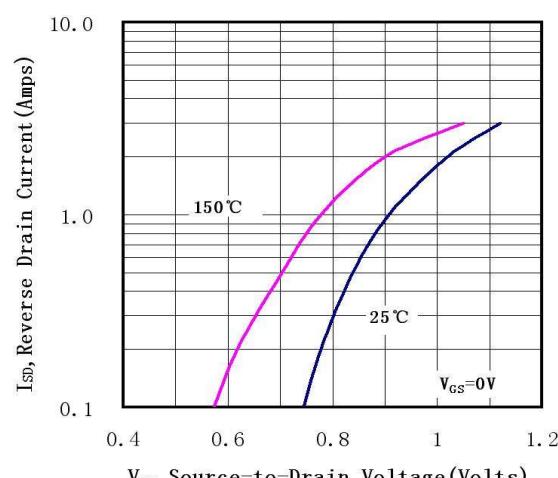


Fig4 Typical Source-Drain Diode Forward Voltage

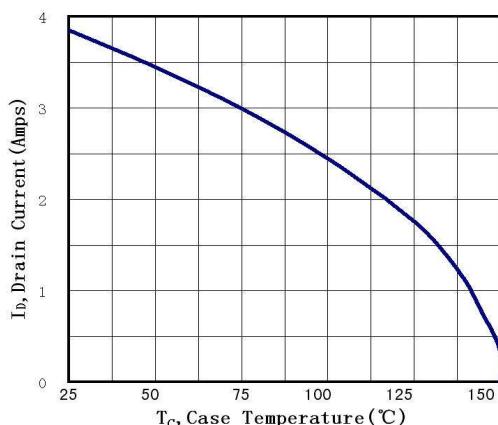


Fig5 Maximum Drain Current Vs. Case Temperature

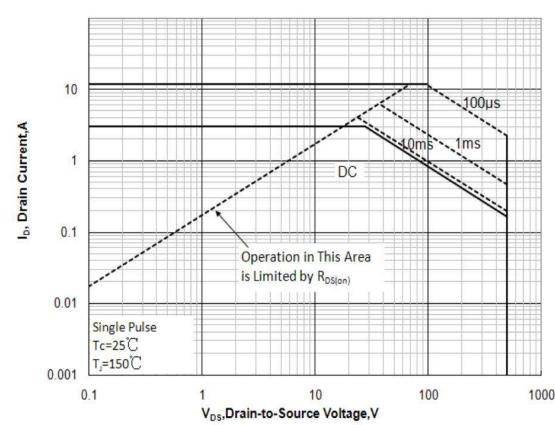
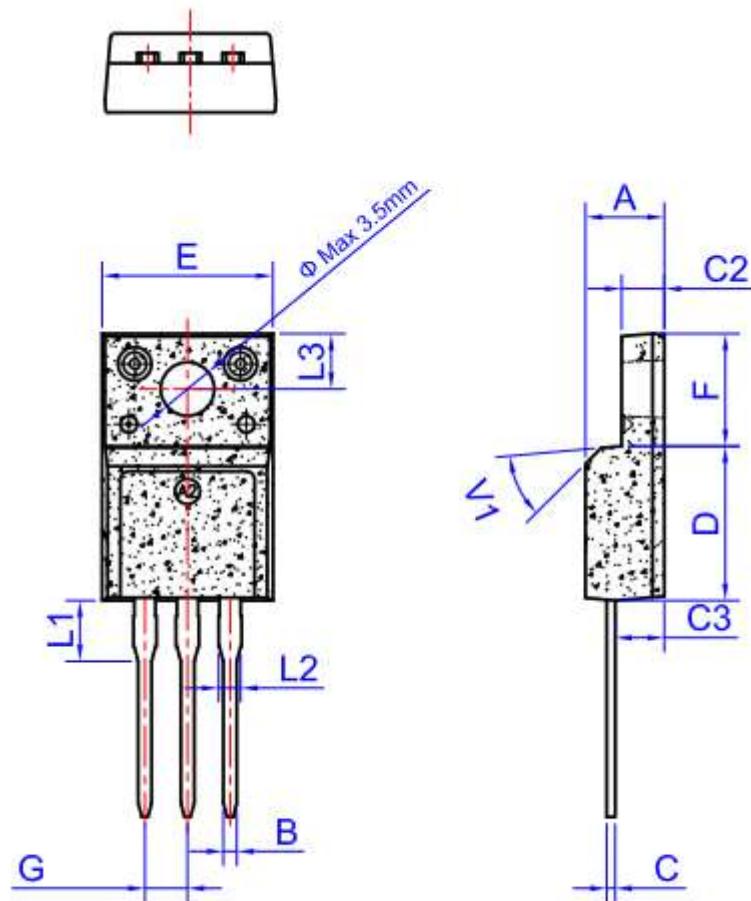


Fig6 Maximum Safe Operating Area

## Package Outlines



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.50		4.90	0.177		0.193
B	0.74	0.80	0.83	0.029	0.031	0.033
C	0.47		0.65	0.019		0.026
C2	2.45		2.75	0.096		0.108
C3	2.60		3.00	0.102		0.118
D	8.80		9.30	0.346		0.366
E	9.80		10.4	0.386		0.410
F	6.40		6.80	0.252		0.268
G		2.54			0.1	
H	28.0		29.8	1.102		1.173
L1		3.63			0.143	
L2	1.14		1.70	0.045		0.067
L3		3.30			0.130	
V1		45°			45°	